Simulation and testbeam analysis of passive CMOS strip sensors Summary of results

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27.02.23





General Information

Sensor Designs

Simulations

Testbeam Analysis

Summary

		Low Dose 30				
	Low Dose 55					
3	2	1	0			
		Regular				
	1					

- Passive sensors produced by LFoundry in 150 nm process with additional backside processing from IZM Berlin
- $(150\pm10)\,\mu m$ thickness, 3-5 k Ω resistivity, 75.5 μm strip pitch, 40 strips per sensor, up to 5 stitch lines
- Two different lengths: 4.1 cm & 2.1 cm
- Three different designs: Regular, Low Dose 30 and 55, developed by University of Bonn
- Irradiation of sensors to different fluences with: 23 MeV protons (KIT), reactor neutrons (Ljubljana), 24 GeV protons (IRRAD@CERN)



Investigated Sensors Regular and Low Dose Design



27.02.23

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Simulations Overview

Overview

- Simulations of all three design in Sentaurus TCAD by Iveta Zatocilova, doping profiles by Marta Baselga
- Sensors simulated as 4 strip structure with vacuum boundary conditions
- Macroscopic electrical characteristics, electric fields and transient currents successfully simulated Low does

100



0

0 50 ×

100

200 CMOS strips simulation and testbeam analysis

2280+1

-8.119e+15

-2.797e+18





Simulations Electric Field Configuration



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Overviev

Electric Field Configuration

Macroscop Characteris tics

Charge Collection

Testbeam Analysis

Summary



100



Low dose 55

- Electric field simulated @100 V
- Stronger electric field gradient for regular design
- Regions of higher electric field shared between strips for lowdose design

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Simulations Macroscopic Characteristics 1

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Overview

Electric Fiel Configuratio

Macroscopic Characteristics

Charge Collection

Testbeam Analysis





Simulations Macroscopic Characteristics 2

Investigated Sensors

Simulation

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Electric Field Configuration

Macroscopic Characteristics

Charge Collection

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Summary



- Bulk capacitance simulated for one strip multiplied number of strips
- Artifact in capacitance not reproduced by simulations

 \Rightarrow Overall very good agreement between simulated and measured IV/CV characteristics



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Simulations

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Electric Field Configuration

Macroscopi Characteris tics

Charge Collection

Testbeam Analysis

Summary

- $\bullet\,$ Simulation electron/hole density of heavy ion penetrating sensor at $45^\circ\,$ angle off-center
- Nicely visible how electron cloud moves faster than hole cloud
- Moving electron cloud also visible in hole density
- Hole cloud pushed away from strip implant due to electric field
- Enables calculation of charge collected by strips

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Testbeam Analysis Testbeam Setup

Investigated Sensors

Simulations

Testbeam Analysis

Testbeam Setup

Corryvreckan

ALiBaBa Eventloadei

Detector Resolution

Detector Efficiency

n-Pixel Efficiency

Summary





- Two testbeam campaigns conducted at the DESY-II testbeam (November 21 and May 22)
- Beam energy of 3 GeV and 3.4 GeV
- EUDET telescope with 6 ALPIDE planes
- ALPIDE sensors: 1024 x 512 pixels, 29.24 μm x 26.88 μm, total area of 30 mm x 15 mm
- DUT monitored by ALiBaVa system, cooled with dry ice in styrofoam box

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Testbeam Analysis Corryvreckan

Investigated Sensors

- Simulations
- Testbeam Analysis
- Testbeam Setup

Corryvreckan

ALiBaBa Eventloade

- Detector Resolution
- Detector Efficiency
- In-Pixel Efficiency

- Created in December 2019 for the reconstruction and analysis of testbeam data
- Modular architecture: Core handling central functionality, (user created) modules for specific reconstruction tasks (ALiBaVaEventLoader module created for this analysis)
- Events processed sequentially, with each module being executed in linear order inside event loop
- Analysis of data a multi-step process:
 - Prealignment of telescope
 - (Iterative) exact alignment of telescope
 - Prealignment of DUT
 - (Iterative) exact alignment of DUT
 - Full analysis





Testbeam Analysis ALiBaVa EventLoader

Investigated Sensors

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Testbeam

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ALiBaBa Eventloader

Detector Resolution

Detector

In-Pixel

Summary



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Testbeam Analysis Comparison of Detector Resolution - Unirradiated

Investigated Sensors

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Detector Resolution

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Summary





 Expected binary resolution: 21.8 μm; measured resolution: ~23.5 μm

- No difference between designs
- No influence of seed cut on resolution, slight increase of resolution with noise cut

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Testbeam Analysis Comparison of Detector Resolution - 1e14

DUT Resolution

for 1e14 lowdose55 sensor @ 130V

Detector

Resolution





- Inconsistencies most probably due to limited statistics for alignment
- ۲ Resolution increases slightly for decreased voltage

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Testbeam Analysis Comparison of Detector Resolution - 3e14

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ALiBaBa Eventloade

- Detector Resolution
- Detector Efficiency

In-Pixel Efficiency

Summary





- Same general trends as for 1e14 sensor
- Resolution better than for unirradiated sensor
- Reason not yet understood complicated due do limited amount of sensors measured in testbeam

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Testbeam Analysis Comparison of Detector Resolution - 1e15

Investigated Sensors

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ALiBaBa Eventloade

- Detector Resolution
- Detector Efficiency

In-Pixel Efficiency

Summary





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DUT Resolution

for 1e15 lowdose30 sensor @ 450V

30



Testbeam Analysis Comparison of Detector Efficiency - <u>Unirradiated</u>

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Detector Resolutio

Detector Efficiency

In-Pixel Efficiency

Summary





 Strong dependence of efficiency on seed cut, no dependence on noise cut

• $\epsilon_{regular} > \epsilon_{lowdose30} > \epsilon_{lowdose55}$

- Efficiency of > 97% for seed cut of: 1.5 (lowdose55), 3 (lowdose30), 3.5 (regular)
- Efficiency decreased for lower voltages

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Testbeam Analysis Comparison of Detector Efficiency - 1e14

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Detector Resolutio

Detector Efficiency

In-Pixel Efficiency

Summary





- Lowdose55 shows stronger dependence on seed cut than other designs
- Maybe possible to recover some efficiency with stricter time cuts

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Testbeam Analysis Comparison of Detector Efficiency - 3e14

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Detector Resolutior

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In-Pixel Efficiency

Summary





• Efficiency increased compared to 1e14 sensor (max 94%)

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Testbeam Analysis Comparison of Detector Efficiency - 1e15

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Testbeam Analysis Comparison of In-Pixel Efficiency - Unirradiated



Simulations

- Testbeam Analysis
- Testbeam Setup
- Corryvreckan
- ALiBaBa Eventloade
- Detector Resolution
- Detector
- In-Pixel Efficiency
- Summary





- Seed cut of 3; Noise cut of 2
- No decrease in efficiency over the entire area of the strip ⇒ Stitch has no effect on efficiency!
- Low efficiency edge is artifact of ROI on telescope planes

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Testbeam Analysis Comparison of In-Pixel Efficiency - 3e14



- In-Pixel Efficiency



x Position [µm]



- Seed cut of 3: Noise cut of 2
- Regular design shows efficiency decrease in inter-strip region
- Still no effect of stitches visible

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Similar for all fluences

-2500

-5000

-7500 -10000

-30 -20 -10 Ó 10 20 30 0.2

0.0



Summary and outlook

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Simulations

Festbeam Analysis

Summary

Summary:

- $\bullet\,$ Simulation of all three designs in TCAD have been conducted
- Results of simulation and measurements agree very well so far
- Unirradiated as well as irradiated sensor have been measured in two testbeam campaigns
- Sensor generally work well, but still a few phenomenons left to explain
- So far no signs of stitches impacting sensor performance!

Outlook:

- Testbeam campaign next week with additional timing plane
- Increased focus on bondpad and egde regions
- Plans to irradiate sensors to higher fluences to test their radiation tolerance

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Simulations

Testbeam Analysis

Summary



Fabian Lex

CMOS strips simulation and testbeam analysis

Image: Image:







Testbeam Analysis

Summar





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Low dose 30



Sensors

Testbeam Analysis





Investigated Sensors

Testbeam





Sensors

Testbeam Analysis





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Testbeam Analysis





Investigated Sensors

Simulations

Testbeam Analysis

Summary





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Simulation

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Summary

